Technical Data ______ CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533



	373 533
00	-00 00
D1	
02	
03	-03 03
D4	04 04
05	- 05 05
D6-	06 06
D7	-07 67
	F -4
οĒ	9205-42421

Octal Transparent Latch, 3-State

CD54/74AC/ACT373 - Non-Inverting CD54/74AC/ACT533 - Inverting

Type Features:

Buffered inputs

Typical propagation delay:
 4.3 ns @ V_{cc} = 5 V, T_A = 25° C, C_L = 50 pF

FUNCTIONAL DIAGRAM

The RCA-CD54/74AC373 and CD54/74AC533 and the CD54/74ACT373 and CD54/74ACT533 octal transparent 3state latches use the RCA ADVANCED CMOS technology. The outputs are transparent to the inputs when the Latch Enable ($\overline{\text{LE}}$) is HIGH. When the Latch Enable ($\overline{\text{LE}}$) goes LOW, the data is latched. The Output Enable ($\overline{\text{OE}}$) controls the 3-state outputs. When the Output Enable ($\overline{\text{OE}}$) is HIGH, the outputs are in the high-impedance state. The latch operation is independent of the state of the Output Enable.

The CD74AC/ACT373 and CD74AC/ACT533 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 to +125°C).

The CD54AC/ACT373 and CD54AC/ACT533, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

Family Features:

- Exceeds 2-kV ESD Protection MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
 Speed of bipolar FAST*/AS/S with significantly
- reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced
- noise immunity at 30% of the supply
- ± 24-mA output drive current
 Fanout to 15 FAST* ICs
 Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

Output Enable	Latch Enable	Data	AC/ACT373 Output	AC/ACT533 Output
L	н	н	н	L
L	н	L	ι	н
L	(L	1	(L	н
L	L	h	н	ι
н	X I	X	Z	z

TRUTH TABLE

Note:

L = Low voltage level

H = High voltage level I = Low voltage level one set-up

time prior to the high to low

latch enable transition

h = High voltage level one set-up time prior to the high to low latch enable transition.

X = Don't Care

Z = High Impedance State

This data sheet is applicable to the CD54/74AC373, CD54/74ACT373, and CD54ACT533. The CD74AC533 and CD74ACT533 were not acquired from Harris Semiconductor.

File Number 1882

CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

MAXIMUM RATINGS, Absolute-Maximum Values:
DC SUPPLY-VOLTAGE (V _{cc})
DC INPUT DIODE CURRENT, I _K (for $V_1 < -0.5$ V or $V_1 > V_{cc} + 0.5$ V) +20 mA
DC OUTPUT DIODE CORRENT, low (for $v_0 < -0.5$ V or $v_0 > V_{cc} + 0.5$ V)
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_0 (for $V_0 > -0.5$ V or $V_0 < V_{cc} + 0.5$ V)
DC Vcc OF GROUND CURRENT (Icc OF IGND)
POWER DISSIPATION PER PACKAGE (Po):
For T _A = -55 to +100°C (PACKAGE TYPE E)
For $I_A = \pm 100$ to ± 125 °C (PACKAGE TYPE E) Derate Linearly at 8 mW/°C to 300 mW
For $I_A = -55$ to $+70^{\circ}$ C (PACKAGE TYPE M)
For $T_A = +70$ to $+125^{\circ}C$ (PACKAGE TYPE M) Derate Linearly at 6 mW/°C to 70 mW
OPERATING-TEMPERATURE HANGE (T_A)
-65 to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 \pm 1/32 in. (1.59 \pm 0.79 mm) from case for 10 s maximum
Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only
*For up to 4 outputs per device; add \pm 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	4.4	LIN		
	1 1 ST C	MIN.	MAX.	UNITS
Supply-Voltage Range, V_{∞}^* : (For $T_A = Full Package-Temperature Range)$	i i mi			
AC Types ACT Types	CO	1.5 4.5	5.5 5.5	v
DC Input or Output Voltage, VI, Vo		0	Vcc	V
Operating Temperature, T _A		-55	+125	°C
Input Rise and Fall Slew Rate, dt/dv at 1.5 V to 3 V(AC Types) at 3.6 V to 5.5 V(AC Types) at 4.5 V to 5.5 V(ACT Types)		0 0 0	50 20 10	ns/V ns/V ns/V

*Unless otherwise specified, all voltages are referenced to ground.

TERMINAL ASSIGNMENT DIAGRAMS



CD54/74AC373, CD54/74ACT373

CD54/74AC533, CD54/74ACT533

Technical Data ____ CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

STATIC ELECTRICAL CHARACTERISTICS: AC Series

						MBIENT	TEMPE	RATURE	(T _A) - °C		
CHARACTERISTI	cs	TEST CO	DITIONS	V _{cc}	+2	25	-40 to	+85	-55 to	+125	UNITS
		V, (V)	l _o (mA)	(Ÿ)	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input				1.5	1.2	—	1.2		1.2		
Voltage	ViH			3	2.1	—	2.1		2.1		v
				5.5	3.85		3.85	—	3.85		
Low-Level Input				1.5		0.3	-	0.3		0.3	
Voltage	ViL			3		0.9		0.9	<u> </u>	0.9	V
				5.5	· _	1.65	—	1.65		1.65	
High-Level Output			-0.05	1.5	1.4		1.4	—	1.4		
Voltage	Vон	ViH	-0.05	3	2.9	<u> </u>	2.9		2.9		
		or	-0.05	4.5	4.4	—	4.4	—	4.4]
		ViL	-4	3	2.58	—	2.48	-	2.4		v
			-24	4.5	3.94		3.8	—	3.7	—] .
		#, * {	-75	5.5 3.85 -	_	—					
		<i>"</i> , " {	-50	5.5	_		3.75		3.85	—]
Low-Level Output			0.05	1.5		0.1	_	0.1	—	0.1	
Voltage	Vol	ViH	0.05	3	-%	0.1	9	0.1		0,1	
		or	0.05	4.5	3 1.	0.1	- 1	0.1	—	0.1]
		VIL	12	3		0.36		0.44	—	0.5	V I
			24	4.5		0.36	_	0.44	—	0.5]
		#, *	75	5.5	-			1.65	—	-]
		#, *	50	5.5		_				1.65]
Input Leakage Current	h	V _{cc} or GND		5.5		±0.1	_	±1	_	±1	μA
3-State Leakage Current	loz	V _{tH} or									
		V_{1L} $V_{O} =$ V_{CC}		5.5	-	±0.5		±5	_	±10	μA
		or GND									
Quiescent Supply Current, MSI	Icc	V _{cc} or GND	0	5.5		8		80	_	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation. *Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

Technical Data

CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

						AMBIEN	Т ТЕМРІ	RATUR	E (T _A) - °	с]
CHARACTERIST	ICS	TEST CO	EST CONDITIONS		+	25	-40 1	o +85	-55 t	o +125	
		V, (V)	l _o (mA)	V _{cc} (V) MIN. MAX.		MIN. MAX.		MIN.	MAX.		
High-Level Input Voltage	Vін			4.5 to 5.5	2	_	2	_	2	_	V
Low-Level Input Voltage	ViL			4.5 to 5.5	_	0.8	_	0.8	-	0.8	v
High-Level Output		ViH	-0.05	4.5	4.4		4.4	-	4.4	<u> </u>	-
Voltage	V _{он}	or ViL	-24	4.5	3.94		3.8		3.7] v
		#, * {	-75	5.5			3.85	—] `
·····			-50	5.5				—	3.85	-	1
Low-Level Output Voltage	V	V _{ін} or	0.05	4.5		0.1		0.1	—	0.1	
vollage	Vol	Vil /	24	4.5	-	0.36		0.44		0.5	
		#, * {	75	5.5			4	1.65		-]
		l l	50	5.5	-	3.0	F The	—	-	1.65	1
Input Leakage Current	łı	V _{cc} or GND		5.5	38 × 35	±0.1	.er	±1		±1	μA
3-State Leakage Current	loz	Vin or Vit			,C	011					
		V _o = V _{cc} or GND		5.5		±0.5	_	±5		.±10	μA
Quiescent Supply Current, MSI	lcc	V _{CC} or GND	0	5.5	—	8	-	80	—	160	μΑ
Additional Quiescent S Current per Input Pi TTL Inputs High 1 Unit Load	Supply n ∆l _{cc}	V _{cc} -2.1		4.5 to 5.5	_	2.4		2.8		3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation. *Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT	LOAD*
INFOI	ACT373	ACT533
ŌĒ	0.87	0.87
Dn	0.5	0.5
ĹĒ	0.8	0.8

*Unit load is Aloc limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

Technical Data ______ CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

PREREQUISITE FOR SWITCHING: AC Series

			AMBI	ENT TEMPE	RATURE (1	Г _А) -°С]
CHARACTERISTICS	SYMBOL	V _{cc} (V)	-40 t	o +85	-55 to	o +125	UNITS
		(*)	MIN.	MAX.	MIN.	MAX.	· .
LE Pulse Width	tw	1.5 3.3* 5†	44 4.9 3.5	-	50 5.6 4		ns
Setup Time Data to LE	tsu	1.5 3.3 5	2 2 2	-	2 2 2		ns
Hold Time Data to LE	tH	1.5 3.3 5	33 3.7 2.6		38 4.2 3		ns

*3.3 V: min. is @ 3 V

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; t,, t = 3 ns, C = 50 pF

			AMBIE	ENT TEMPE	RATURE (T	λ) - °C	
CHARACTERISTICS	SYMBOL	V _{cc}	-40 te	o +85 🔬	-55 to	+125	
		(Ŭ)	MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Qn 373	tе∟н tен∟	1.5 3.3* 5†	3.1 2.2	96 10.8 7.7		106 11.9 8.5	ns
533	tрцн tрн	1.5 3.3 5	3.8 2.7	119 13.4 9.5	3.7 2.6	131 14.7 10.5	ns
LE on Qn 373	tplh tphl	1.5 3.3 5	 4.3 3.1	136 15.2 10.9	4.2 3	150 16.8 12	ns
533	telh tehl	1.5 3.3 5	 4.3 3.1	136 15.3 10.9	4.2 3	150 16.8 12	ns
Output Enable Times	tezi. tezh	1.5 3.3 5	 4.1 2.7	119 14.4 9.5	4 2.6	131 15.8 10.5	ns
Output Disable Times	tpiz tphz	1.5 3.3 5	 3.7 3	131 13.1 10.5		144 14.4 11.5	ns
Power Dissipation Capacitance	CPD§		63	Тур.	63	Тур	pF
Min. (Valley) Vон During Switching of Other Outputs (Output Under Test Not Switching)	During Switching of Other Outputs See 5			4 Typ. @ 25°C			
Max. (Peak) Vo⊾ During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5		1 Typ. (@ 25° C		V
Input Capacitance	Cı	_	_	10		10	pF
3-State Output Capacitance	Co	_		15	—	15	pF

*3.3 V: min. is @ 3.6 V max. is @ 3 V

†5 V: min. is @ 5.5 V max. is @ 4.5 V $V_{cc} =$ supply voltage.

_ Technical Data CD54/74AC373, CD54/74AC533 CD54/74ACT373, CD54/74ACT533

PREREQUISITE FOR SWITCHING: ACT Series

			AMBI	ENT TEMP	ERATURE (1	「∧) -°C	
CHARACTERISTICS	SYMBOL	V _{cc} (V)	-40 to +85		-55 to +125		
		(*)	MIN.	MAX.	MIN.	MAX.	1
TÊ Pulse Width	tw	5†	3.6	-	4		ns
Setup Time Data to LE	tsu	5	2	_	2		ns
Hold Time Data to LE	t _H	5	2.7		3		ns

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: ACT Series; t,, t, = 3 ns, CL = 50 pF

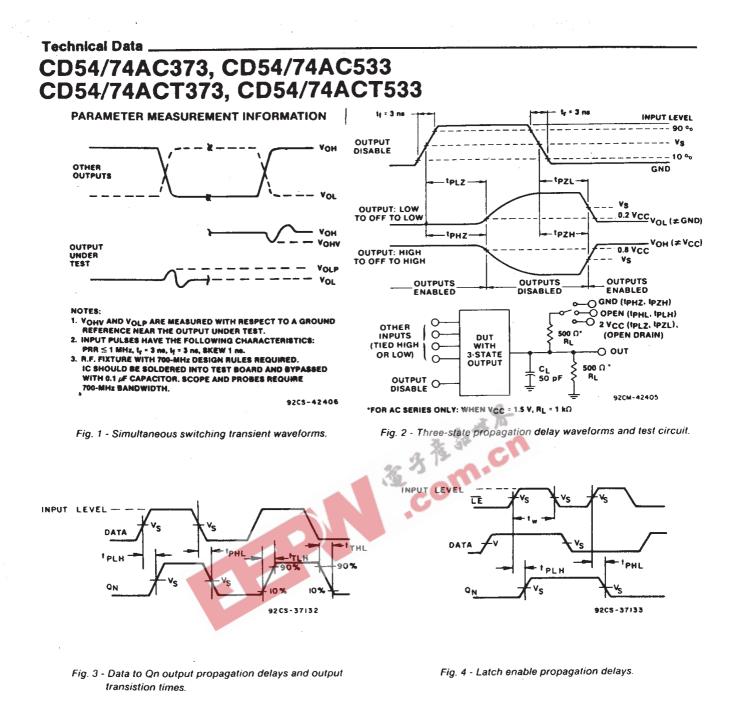
			AMBI	ENT TEMPI	ERATURE (T _A) -°C	1
CHARACTERISTICS	SYMBOL	V _{cc} (V)		lo +85	1	o +125	UNITS
			MIN.	MAX.	MIN.	MAX.	1
Propagation Delays: Data to Qn 373	tрін	51	2.7	9.5	2.6	10.4	
533	т тень	5†	3 3	10.4	2.9	11.4	ns
LE to Qn 373 533	t _{PLH} tphL	5 🥈	3.1	11.4	3	12.5	ns
Output Enable Times	lpzi lpzh	5	3.5	12.3	3.4	13.5	ns
Output Disable Times	tplz tphz	5	3.2	11.4	3.1	12.5	ns
Power Dissipation Capacitance	CPD§		63	тур.	63	Гур.	pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	Vонv See Fig. 1	5	4 Typ. @ 25°C			v	
Max. (Peak) VoL During Switching of Other Outputs (Output Under Test Not Switching)	Volp See Fig. 1	5		1 Тур. (@ 25°C	umma da i di ju	v
Input Capacitance	Cı		_	10	_	10	pF
3-State Output Capacitance	Co	_	_	15	_	15	pF

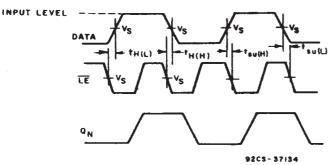
†5 V: min. is @ 5.5 V

max. is @ 4.5 V

§CPD is used to determine the dynamic power consumption, per latch. $P_{D} = V_{CC}^{2} f_{i} (C_{PD} + C_{L}) + V_{CC} \Delta I_{CC} \text{ where } f_{i} = \text{input frequency} \\ C_{L} = \text{output load capacitance}$

 V_{cc} = supply voltage.





	CD54/74AC	CD54/74ACT
Input Level	Vcc	3 V
Input Switching Voltage, Vs	0.5 V _{cc}	1.5 V
Output Switching Voltage, Vs	0.5 V _{cc}	0.5 V _{cc}

Fig. 5 - Latch enable prerequisite times.

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